

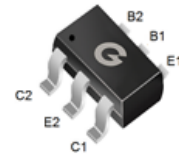
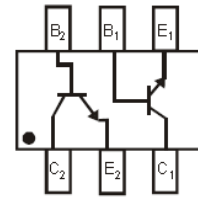
Features

- Epitaxial planar die construction
- Complementary PNP type available (IMT4)

HF

Mechanical Data

- Case: SOT-23-6L
- Molding compound: UL flammability classification rating 94V-0
- Terminals: Tin-plated; solderability per MIL-STD-202, Method 208



SOT-23-6L

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
IMX8	SOT-23-6L	3000 pcs / Tape & Reel	KX8

Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Collector-Base Breakdown Voltage	V _{CBO}	120	V
Collector-Emitter Breakdown Voltage	V _{CEO}	120	V
Emitter-Base Breakdown Voltage	V _{EBO}	5	V
Collector Current (Continuous)	I _C	0.05	A

Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation *1	P _D	0.3	W
Thermal Resistance Junction-to-Air *1	R _{θJA}	417	°C/W
Junction Temperature	T _J	-55 ~ +150	°C
Storage Temperature Range	T _{STG}	-55 ~ +150	°C

Note 1: Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Inc.

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C = 50\mu\text{A}$, $I_E = 0$	120	-	-	V
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	$I_C = 1\text{mA}$, $I_B = 0$	120	-	-	V
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E = 50\mu\text{A}$, $I_C = 0$	5	-	-	V
Collector Cut-off Current	I_{CBO}	$V_{CB} = 100\text{V}$, $I_E = 0$	-	-	0.5	μA
Emitter Cut-off Current	I_{EBO}	$V_{EB} = 4\text{V}$, $I_C = 0$	-	-	0.5	μA
DC Current Gain	h_{FE}	$V_{CE} = 6\text{V}$, $I_C = 2\text{mA}$	180	-	820	-
Collector-emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 10\text{mA}$, $I_B = 1\text{mA}$	-	-	0.5	V
Transition Frequency	f_T	$I_C = 2\text{mA}$, $V_{CE} = 12\text{V}$ $f = 100\text{MHz}$	-	140	-	MHZ

Ratings and Characteristic Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

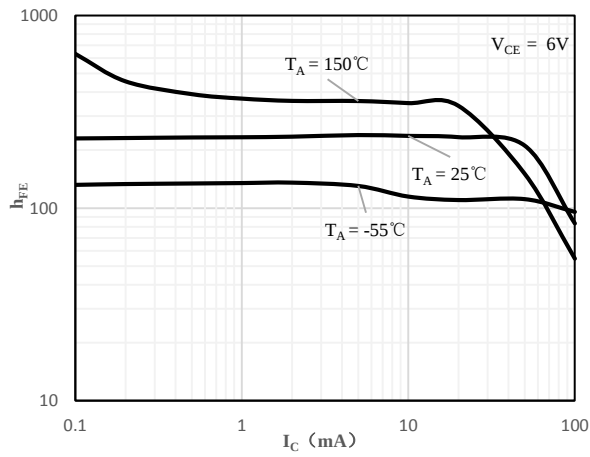


Fig 1 h_{FE} vs. I_C

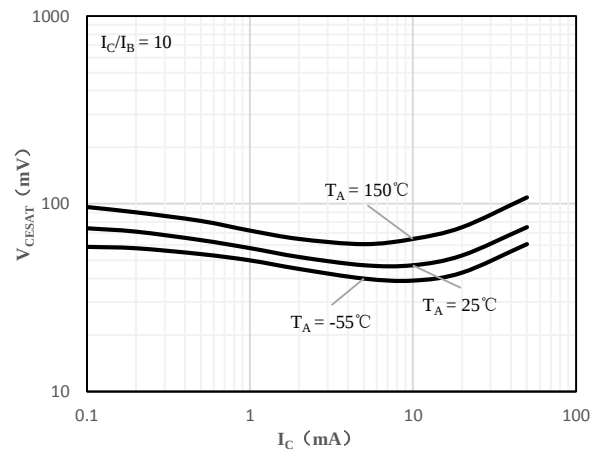


Fig 2 $V_{CE(sat)}$ vs. I_C

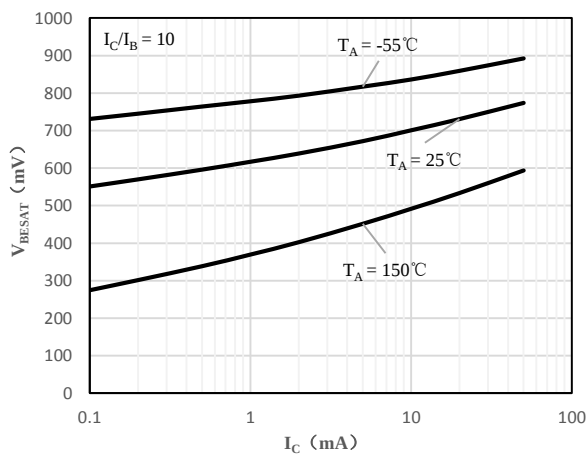


Fig 3 $V_{BE(sat)}$ vs. I_C

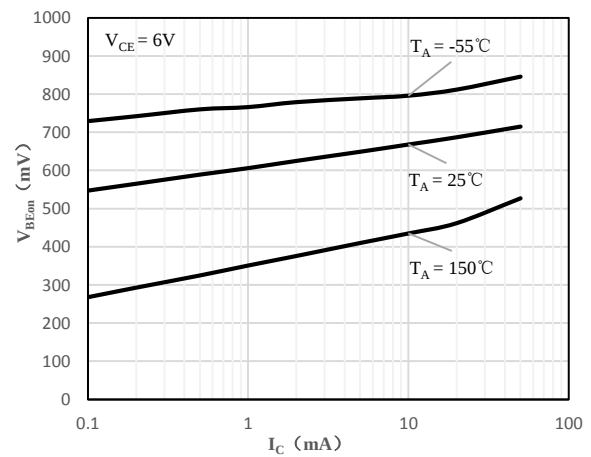
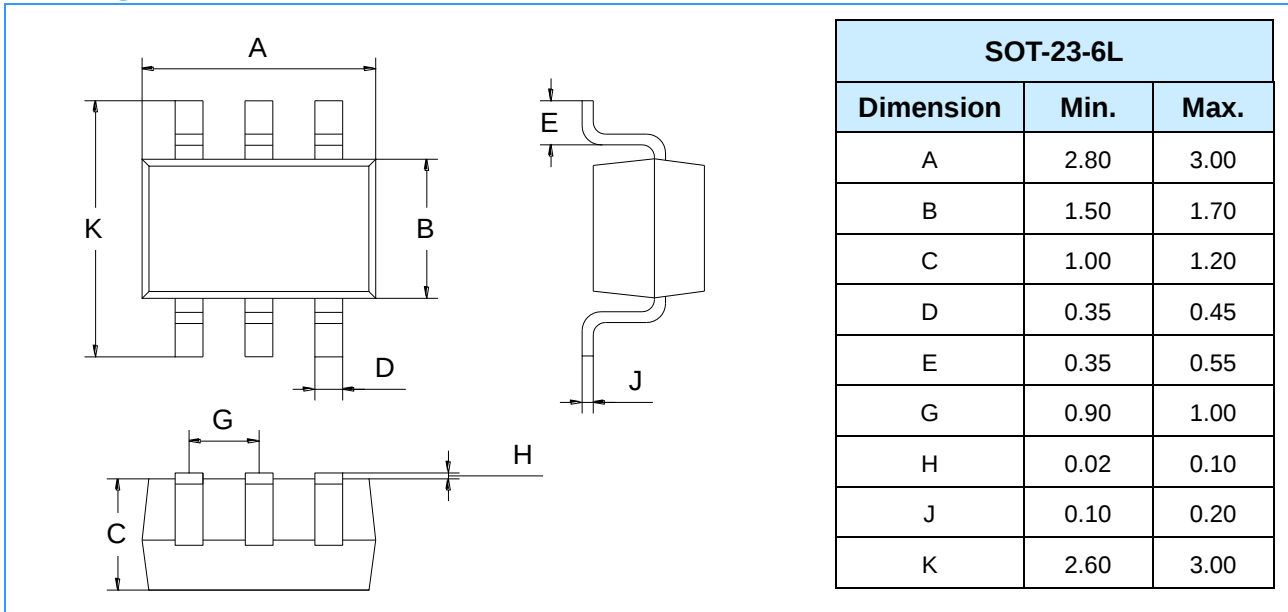
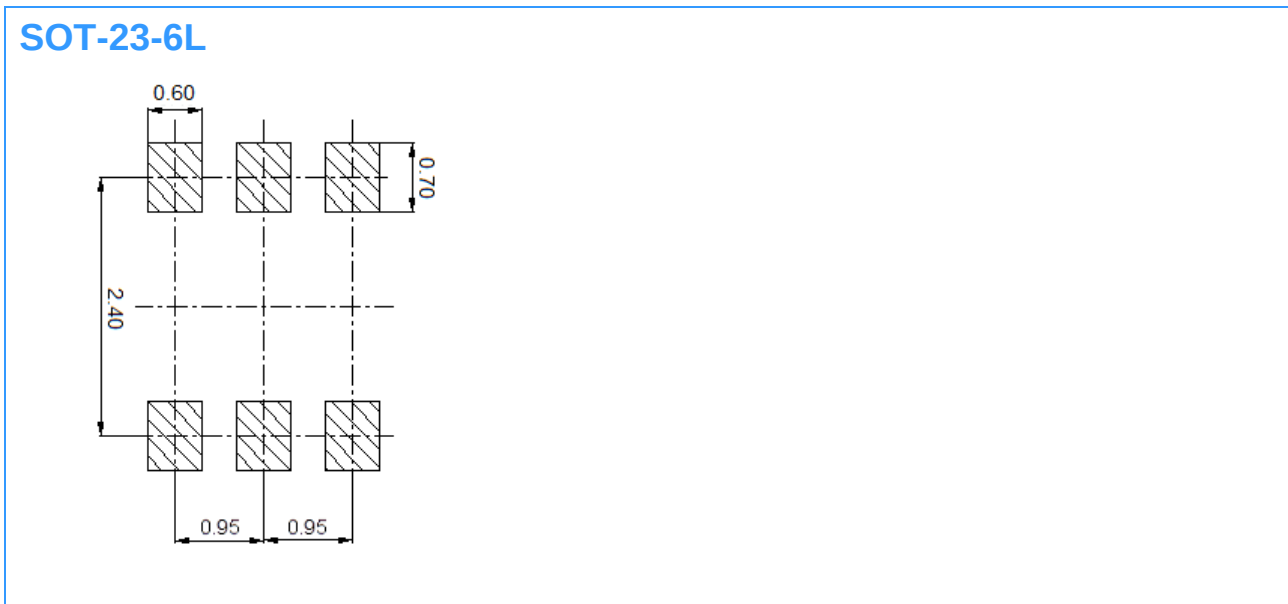


Fig 4 $V_{BE(on)}$ vs. I_C

Package Outline Dimensions (Unit: mm)



Mounting Pad Layout (Unit: mm)



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